IPC is seeking presentations for our 3rd annual High Reliability Forum for electronics subjected to harsh use environments on the following topics:

- Mechanical stress reliability - vibration and shock Methods (software) for predicting reliability
- Failure Modes Effects Analysis (FMEA)
- Thermal Mitigation
- Thermal Stress Test Methods
- HDI Reliability
- Microvia Failures and Testing Methods
- Microvia Reliability
- Design for Reliability
- Design Rules for Spacing and Staggered Vias
- Failures Related to Laminate Materials
- Materials Compatibility
- System-level effects on Solder Joint Reliability
- Assembly Tests for Solder Joint Reliability

Presentations should be noncommercial and describe significant results from experiments, emphasize new techniques, discuss trends of interest and contain technical and/or appropriate test results. Presentations should be 45 minutes, including time for questions and answers.

If you’re interested in presenting at this important industry event, please submit a brief abstract along with the title of your presentation to AliciaBalonek@ipc.org.